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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

application of:  
William Hong et al.

Serial No.: 10/714,985

Filed: November 17, 2003

For: Copper CMP Defect Reduction By Extra Slurry Polish

§ Attorney Docket No.: 24061.514  
§ § TSMC2003-0299  
§ Customer No. 42717  
§ Group Art Unit: 2813  
§ Examiner: Thanh T. Nguyen  
§ Conf. No.: 2268

TRANSMITTAL

Mail Stop: AMENDMENT  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

Enclosed for filing in the above-identified patent application.

1. Amendment in Response to Office Action dated August 24, 2004;
2. Revocation/New Power of Attorney by Assignee of Entire Interest Including Certification for Taking Action by Assignee Under 37 CFR 3.73(b);
3. Check in the amount of \$72.00;
4. This transmittal (in duplicate); and
5. Return Receipt Postcard

The Director is authorized to charge any deficiency fees or credit any overpayments to Deposit Account No. 08-1394 of Haynes and Boone, LLP.

Respectfully submitted,

David M. O'Dell  
Reg. No. 42,044

Date: 11-5-04

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CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on the date indicated below:

Bonnie Boyle

11-8-04

Date